

# NLX2G04

## Dual Inverter

The NLX2G04 MiniGate™ is an advanced high-speed CMOS dual inverter in ultra-small footprint.

The NLX2G04 input and output structures provide protection when voltages up to 7.0 V are applied, regardless of the supply voltage.

### Features

- High Speed:  $t_{PD} = 1.8 \text{ ns}$  (Typ) @  $V_{CC} = 5.0 \text{ V}$
- Low Power Dissipation:  $I_{CC} = 1 \mu\text{A}$  (Max) at  $T_A = 25^\circ\text{C}$
- Power Down Protection Provided on inputs
- Balanced Propagation Delays
- Overvoltage Tolerant (OVT) Input and Output Pins
- Ultra-Small Packages
- These are Pb-Free Devices

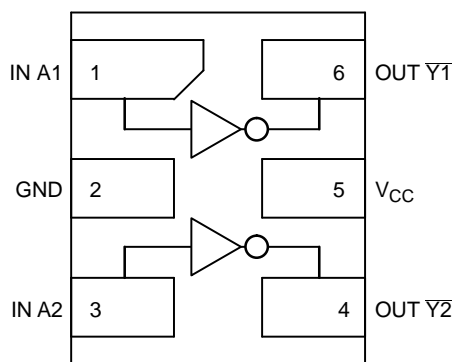


Figure 1. Pinout (Top View)

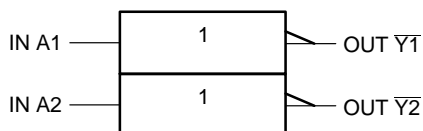


Figure 2. Logic Symbol

### PIN ASSIGNMENT

1	IN A1
2	GND
3	IN A2
4	OUT $\overline{Y2}$
5	$V_{CC}$
6	OUT $\overline{Y1}$

### FUNCTION TABLE

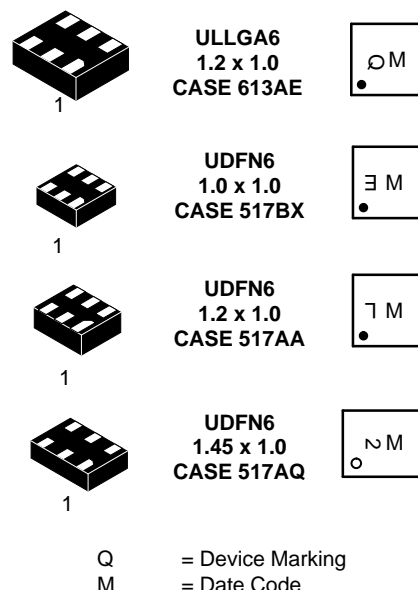
A	Y
L	H
H	L



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### MARKING DIAGRAMS



### ORDERING INFORMATION

See detailed ordering and shipping information on page 5 of this data sheet.

# NLX2G04

## MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
$V_{CC}$	DC Supply Voltage	-0.5 to +7.0	V
$V_{IN}$	DC Input Voltage	-0.5 to +7.0	V
$V_{OUT}$	DC Output Voltage	-0.5 to +7.0	V
$I_{IK}$	DC Input Diode Current $V_{IN} < GND$	-50	mA
$I_{OK}$	DC Output Diode Current $V_{OUT} < GND$	-50	mA
$I_O$	DC Output Source/Sink Current	$\pm 50$	mA
$I_{CC}$	DC Supply Current Per Supply Pin	$\pm 100$	mA
$I_{GND}$	DC Ground Current per Ground Pin	$\pm 100$	mA
$T_{STG}$	Storage Temperature Range	-65 to +150	°C
$T_L$	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
$T_J$	Junction Temperature Under Bias	150	°C
MSL	Moisture Sensitivity	Level 1	
$F_R$	Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
$I_{LATCHUP}$	Latchup Performance Above $V_{CC}$ and Below GND at 125°C (Note 2)	$\pm 500$	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.
2. Tested to EIA / JESD78.

## RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
$V_{CC}$	Positive DC Supply Voltage	1.65	5.5	V
$V_{IN}$	Digital Input Voltage	0	5.5	V
$V_{OUT}$	Output Voltage	0	5.5	V
$T_A$	Operating Free-Air Temperature	-55	+125	°C
$\Delta t/\Delta V$	Input Transition Rise or Fall Rate $V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$ $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ $V_{CC} = 5.0\text{ V} \pm 0.5\text{ V}$	0 0 0	20 10 5	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Conditions	V <sub>CC</sub> (V)	T <sub>A</sub> = 25°C			T <sub>A</sub> = +85°C		T <sub>A</sub> = -55°C to +125°C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
V <sub>IH</sub>	Low-Level Input Voltage		1.65–1.95	0.75 x V <sub>CC</sub>			0.75 x V <sub>CC</sub>		0.75 x V <sub>CC</sub>		V
			2.3 to 5.5	0.70 x V <sub>CC</sub>			0.70 x V <sub>CC</sub>		0.70 x V <sub>CC</sub>		
V <sub>IL</sub>	Low-Level Input Voltage		1.65–1.95			0.25 x V <sub>CC</sub>		0.25 x V <sub>CC</sub>		0.25 x V <sub>CC</sub>	V
			2.3 – 5.5			0.30 x V <sub>CC</sub>		0.30 x V <sub>CC</sub>		0.30 x V <sub>CC</sub>	
V <sub>OH</sub>	High-Level Output Voltage	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OH</sub> = -100 µA	1.65 – 5.5	V <sub>CC</sub> -0.1	V <sub>CC</sub>		V <sub>CC</sub> -0.1		V <sub>CC</sub> -0.1		V
		V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OH</sub> = -4 mA	1.65	1.29	1.52		1.29		1.29		
		I <sub>OH</sub> = -8 mA	2.3	1.9	2.1		1.9		1.9		
		I <sub>OH</sub> = -12 mA	2.7	2.2	2.4		2.2		2.2		
		I <sub>OH</sub> = -16 mA	3.0	2.4	2.7		2.4		2.4		
		I <sub>OH</sub> = -24 mA	3.0	2.3	2.5		2.3		2.3		
		I <sub>OH</sub> = -32 mA	4.5	3.8	4.0		3.8		3.8		
V <sub>OL</sub>	Low-Level Output Voltage	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OL</sub> = 100 µA	1.65 – 5.5			0.1		0.1		0.1	V
		V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OH</sub> = -4 mA	1.65		0.08	0.24		0.24		0.24	
		I <sub>OH</sub> = -8 mA	2.3		0.2	0.3		0.3		0.3	
		I <sub>OH</sub> = -12 mA	2.7		0.22	0.4		0.4		0.4	
		I <sub>OH</sub> = -16 mA	3.0		0.28	0.4		0.4		0.4	
		I <sub>OH</sub> = -24 mA	3.0		0.38	0.55		0.55		0.55	
		I <sub>OH</sub> = -32 mA	4.5		0.42	0.55		0.55		0.55	
I <sub>IN</sub>	Input Leakage Current	0 ≤ V <sub>IN</sub> ≤ 5.5 V	0 to 5.5			±0.1		±1.0		±1.0	µA
I <sub>OFF</sub>	Power-Off Output Leakage Current	V <sub>IN</sub> or V <sub>OUT</sub> = 5.5 V	0			1.0		10		10	µA
I <sub>CC</sub>	Quiescent Supply Current	0 ≤ V <sub>IN</sub> ≤ V <sub>CC</sub>	5.5			1.0		10		10	µA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

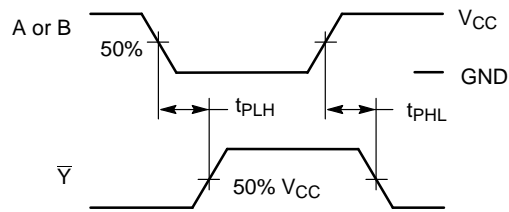
# NLX2G04

## AC ELECTRICAL CHARACTERISTICS (Input $t_r = t_f = 3.0$ nS)

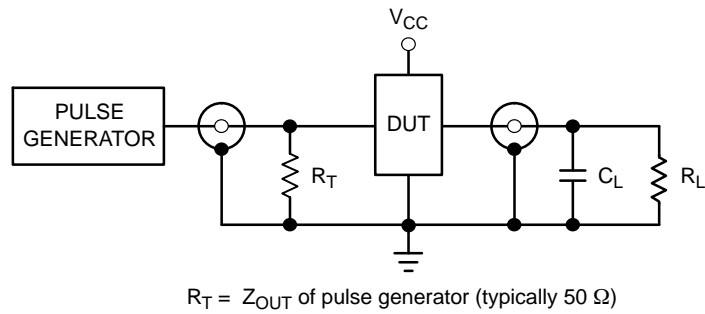
Symbol	Parameter	V <sub>CC</sub> (V)	Test Condition	T <sub>A</sub> = 25°C			T <sub>A</sub> = -55°C to +125°C		Unit
				Min	Typ	Max	Min	Max	
t <sub>PLH</sub> , t <sub>PHL</sub>	Propagation Delay, Input A to Output Y	1.65	R <sub>L</sub> = 1 MΩ, C <sub>L</sub> = 15 pF	1.8	2.3	9.2	1.8	11	ns
		1.8	R <sub>L</sub> = 1 MΩ, C <sub>L</sub> = 15 pF	1.8	4.4	7.6	1.2	8.4	
		2.3–2.7	R <sub>L</sub> = 1 MΩ, C <sub>L</sub> = 15 pF	1.2	3.0	5.1	1.2	5.6	
		3.0–3.6	R <sub>L</sub> = 1 MΩ, C <sub>L</sub> = 15 pF	0.8	2.2	3.4	0.8	3.8	
			R <sub>L</sub> = 500 Ω, C <sub>L</sub> = 50 pF	1.2	2.9	4.5	1.2	5.0	
		4.5–5.5	R <sub>L</sub> = 1 MΩ, C <sub>L</sub> = 15 pF	0.5	1.8	2.8	0.5	3.1	
			R <sub>L</sub> = 500 Ω, C <sub>L</sub> = 50 pF	0.8	2.3	3.6	0.8	4.0	
C <sub>IN</sub>	Input Capacitance	5.5	V <sub>IN</sub> = 0 V or V <sub>CC</sub>		2.5				pF
C <sub>PD</sub>	Power Dissipation Capacitance (Note 3)	3.3 5.5	10 MHz V <sub>IN</sub> = 0 V or V <sub>CC</sub>		9 11				pF

3. C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the dynamic operating current consumption without load. Average operating current can be obtained by the equation  $I_{CC(OPR)} = C_{PD} \cdot V_{CC} \cdot f_{in} + I_{CC}$ . C<sub>PD</sub> is used to determine the no-load dynamic power consumption:  $P_D = C_{PD} \cdot V_{CC}^2 \cdot f_{in} + I_{CC} \cdot V_{CC}$ .

## NLX2G04



**Figure 3. Switching Waveforms**



**Figure 4. Test Circuit**

### ORDERING INFORMATION

Device	Package	Shipping†
NLX2G04BMX1TCG	ULLGA6, 1.2 x 1.0, 0.4P (Pb-Free)	3000 / Tape & Reel
NLX2G04MUTCG	UDFN6, 1.2 x 1.0, 0.4P (Pb-Free)	3000 / Tape & Reel
NLX2G04AMUTCG	UDFN6, 1.45 x 1.0, 0.5P (Pb-Free)	3000 / Tape & Reel
NLX2G04CMUTCG	UDFN6, 1.0 x 1.0, 0.35P (Pb-Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

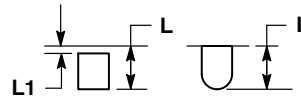
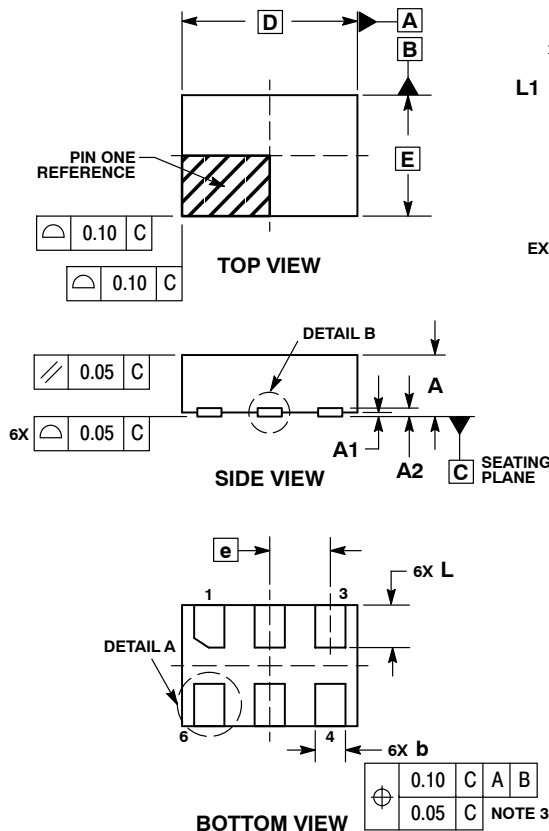
# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



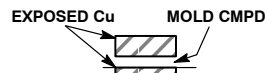
SCALE 4:1

UDFN6, 1.45x1.0, 0.5P  
CASE 517AQ  
ISSUE O

DATE 15 MAY 2008



**DETAIL A**  
OPTIONAL  
CONSTRUCTIONS



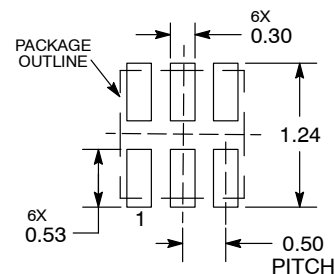
**DETAIL B**  
OPTIONAL  
CONSTRUCTIONS

## NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.

MILLIMETERS		
DIM	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A2	0.07	REF
b	0.20	0.30
D	1.45	BSC
E	1.00	BSC
e	0.50	BSC
L	0.30	0.40
L1	—	0.15

## MOUNTING FOOTPRINT



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## GENERIC MARKING DIAGRAM\*



X = Specific Device Code  
M = Date Code

\*This information is generic. Please refer to device data sheet for actual part marking.  
Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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<b>DESCRIPTION:</b>	<b>UDFN6, 1.45x1.0, 0.5P</b>	<b>PAGE 1 OF 1</b>

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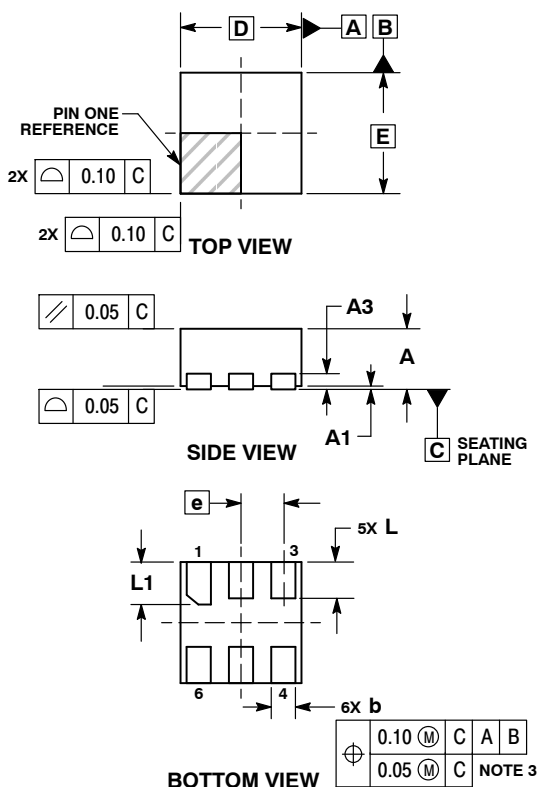
# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SCALE 4:1

UDFN6, 1x1, 0.35P  
CASE 517BX  
ISSUE O

DATE 18 MAY 2011

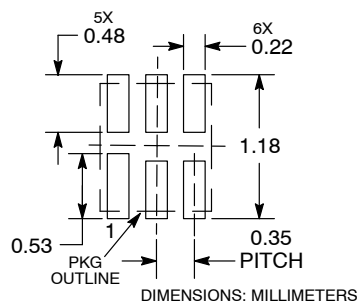


## NOTES:

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2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP.
4. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

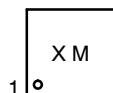
MILLIMETERS		
DIM	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.13	REF
b	0.12	0.22
D	1.00	BSC
E	1.00	BSC
e	0.35	BSC
L	0.25	0.35
L1	0.30	0.40

## RECOMMENDED SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## GENERIC MARKING DIAGRAM\*



X = Specific Device Code  
M = Date Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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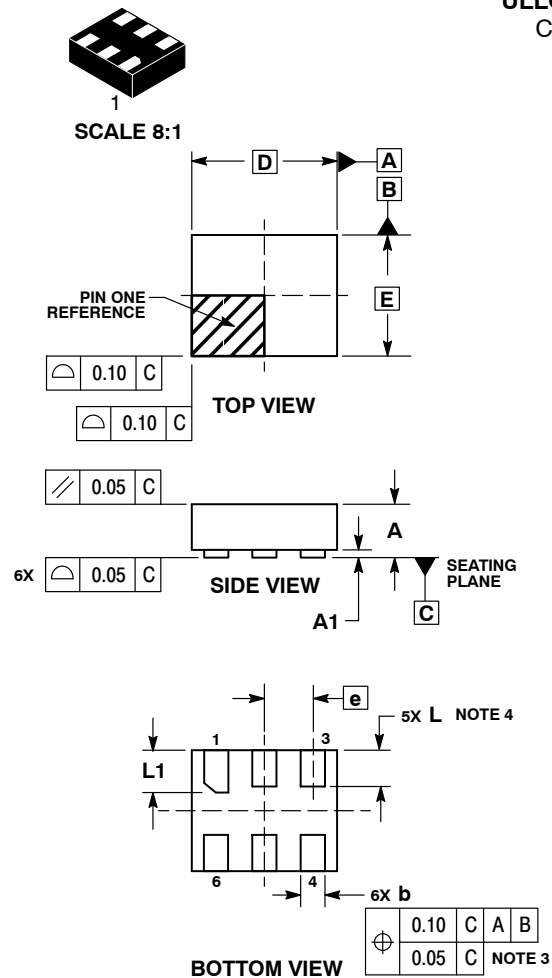
## PACKAGE DIMENSIONS

ON Semiconductor®

ON

ULLGA6, 1.2x1.0, 0.4P  
CASE 613AE-01  
ISSUE A

DATE 06 FEB 2008

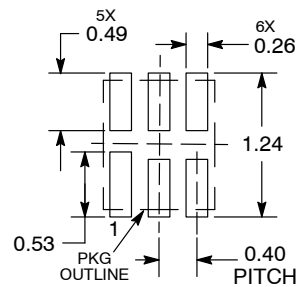


### NOTES:

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2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
4. A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALLOWED.

MILLIMETERS		
DIM	MIN	MAX
A	0.00	0.40
A1	0.00	0.05
b	0.15	0.25
D	1.20 BSC	
E	1.00 BSC	
e	0.40 BSC	
L	0.25	0.35
L1	0.35	0.45

### MOUNTING FOOTPRINT SOLDERMASK DEFINED\*



DIMENSIONS: MILLIMETERS

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